PRINTED CIRCUIT BOARDS

INTERCONNECTION CARRIERS

State of the Art: PCB's	Revisio	Datum:	Seite:
PRINTED CIRCUIT BOARDS	**01**	**4.11.2001**	**1/1**

Schematic Key for Multilayer and HDI-Technology Build-Ups

a	b	c	d	e	f	g + h+ i
05	**251**	**FR4**	**35**	**L71.35**	**P18_10**	**S1**

columns and equal kind of positions are separated by "_". Equal prefixes in one column are reduced to one.

05_251_FR4_35_L71.35_p18_10_s1

Layers	in µ	Material	Build-Up	Assembly
Layer-1	35µ	Copper		B
	100µ	Prepreg	(100 µ PrePreg-Type: 2125)	B
	180µ	Prepreg	(180 µ PrePreg-Type: 7628)	B
Layer-2	35µ	Copper		A1, B
	710µ	L-FR4		A1, B
Layer-3	35µ	Copper		A1, B
	180µ	Prepreg		B
	180µ	Prepreg		B
Layer-4	35µ	Copper		A2, B
	710µ	L-FR4		A2, B
	180µ	Prepreg		B
	100µ	Prepreg		B
Layer-99	35µ	Copper		B

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